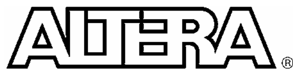

PROCESS CHANGE NOTIFICATION PCN0415

ADDITIONAL MOLD COMPOUND FOR FBGA PACKAGES
FROM ASE MALAYSIA

Change Description:

The Nitto Denko HC100-XJ series mold compound is being added as an additional mold compound choice for Altera® FineLine BGA® packages assembled at ASE Malaysia. This change does not affect form, fit or function.

Reason for Change:

In addition to supporting Pb free and green package requirements, Nitto Denko's HC100-XJAA mold compound was found to provide superior performance with low warpage, low wire sweep, and high moisture reliability. This change is in accordance with Altera's plan to adopt Pb-free mold compound as the standard mold compound for all products in support of world wide environmental initiatives.

Products Affected:

All Altera devices assembled at ASE Malaysia on FineLine BGA packages with 100, 256, 324, 400, 484, and 672 ball counts will be standardized to this mold compound.

Product Traceability and Transition Dates:

This change will be implemented beginning February 2005. Customers may receive product molded with HC100-XJ series mold compound starting with top mark date codes of 0507. Altera maintains a unique trace code marking on the units that can identify the mold compound used if required.

Contact:

For more information, please contact your local Altera sales representative or contact whoria@altera.com at Altera Customer Quality Engineering Department.